


<b>AMENDMENT TRANSMITTAL LETTER (Large Entity)</b>			Docket No. <b>OKI.244</b>		
Applicant(s): <b>Ken Ogura</b>					
Serial No. <b>09/883,363</b>	Filing Date <b>June 19, 2001</b>	Examiner <b>H. Nguyen</b>	Group, Art Unit <b>2812</b>		
Invention: <b>CONDUCTOR POSTS, CONSTRUCTION FOR AND METHOD OF FABRICATING SEMICONDUCTOR INTEGRATED CIRCUIT CHIPS USING THE CONDUCTOR POST, AND METHOD OF PROBING SEMICONDUCTOR INTEGRATED CIRCUIT CHIPS</b>					
<u>TO THE ASSISTANT COMMISSIONER FOR PATENTS:</u>					
Transmitted herewith is an amendment in the above-identified application. The fee has been calculated and is transmitted as shown below.					
<b>CLAIMS AS AMENDED</b>					
	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	13 -	24 =	0 x	\$18.00	\$0.00
INDEP. CLAIMS	2 -	5 =	0 x	\$84.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
<b>TOTAL ADDITIONAL FEE FOR THIS AMENDMENT</b>					<b>\$0.00</b>
<input checked="" type="checkbox"/> No additional fee is required for amendment. <input type="checkbox"/> Please charge Deposit Account No. _____ in the amount of _____ A duplicate copy of this sheet is enclosed. <input type="checkbox"/> A check in the amount of _____ to cover the filing fee is enclosed. <input checked="" type="checkbox"/> The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. <b>50-0238</b> A duplicate copy of this sheet is enclosed. <input checked="" type="checkbox"/> Any additional filing fees required under 37 C.F.R. 1.16. <input checked="" type="checkbox"/> Any patent application processing fees under 37 CFR 1.17.					
 Signature			Dated: <b>December 30, 2002</b>		
<b>ANDREW J. TELESZ, JR.</b> <b>REG. NO. 33,581</b>  <b>VOLENTINE FRANCOS, P.L.L.C.</b> <b>12200 SUNRISE VALLEY DRIVE, SUITE 150</b> <b>RESTON, VA 20191</b>  <b>TEL. NO. (703) 715-0870</b>					
I certify that this document and fee is being deposited on _____ with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.  <div style="text-align: center; border-top: 1px solid black; margin-top: 20px;">           Signature of Person Mailing Correspondence         </div> <div style="text-align: center; border-top: 1px solid black; margin-top: 20px;">           Typed or Printed Name of Person Mailing Correspondence         </div>					
CC:					



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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT APPLICATION of

Ken Ogura

Group Art Unit: 2812

Serial No.: 09/883,363

Examiner: H. Nguyen

Filed: June 19, 2001

For: CONDUCTOR POSTS, CONSTRUCTION FOR AND METHOD OF  
FABRICATING SEMICONDUCTOR INTEGRATED CIRCUIT CHIPS USING  
THE CONDUCTOR POST, AND METHOD OF PROBING SEMICONDUCTOR  
INTEGRATED CIRCUIT CHIPS

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**AMENDMENT**

Honorable Assistant Commissioner for Patents  
Washington, D.C. 20231

Date: December 30, 2002

Sir:

In response to the Office Action dated September 30, 2002, the following  
amendments and remarks are respectfully submitted in connection with the above-  
identified application.

**In the Specification:**

Replace the paragraph beginning on page 29 line 14 with the following  
paragraph:

B<sup>1</sup>  
An electrode pad 14, a first insulating layer 12, a first photosensitive material  
layer 60, and a seal member layer 64A are formed on an IC chip 10 shown in FIG. 24A  
in the same manner as the IC chip 10 of the first embodiment of the invention (See FIG.  
1E). Then, as shown in FIG. 24B, the second photosensitive material layer 62 is